



Description

The XPX3616RX uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

- High power and current handling capability
- Lead free product is acquired
- Surface mount package

N-Channel

$V_{DS} = 30V, I_D = 28A$

$R_{DS(ON)} = 9m\Omega @ V_{GS} = 10V$

$R_{DS(ON)} = 13m\Omega @ V_{GS} = 4.5V$

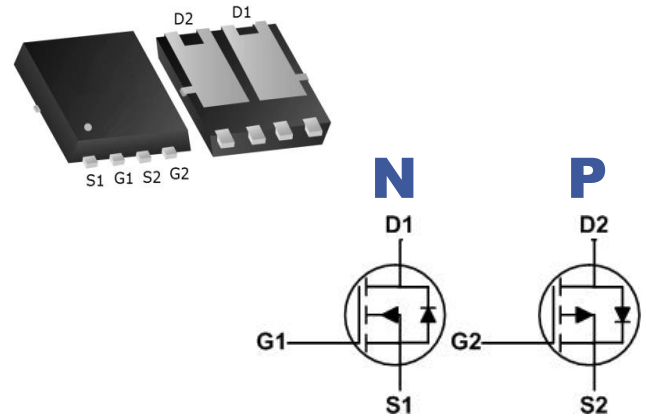
P-Channel

$V_{DS} = -30V, I_D = -19.7A$

$R_{DS(ON)} = 21m\Omega @ V_{GS} = -10V$

$R_{DS(ON)} = 33m\Omega @ V_{GS} = -4.5V$

PDFN3333-8L Pin Configuration



Product ID	Pack	Marking	Qty(PCS)
XPX3616RX	PDFN3*3-8	XPX3616 XXX YYYY	5000

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	N-Ch	P-Ch	Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	28	-19.7	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	22.5	-17.5	A
I_{DM}	Pulsed Drain Current ²	84	-59.1	A
EAS	Single Pulse Avalanche Energy ³	89	78	mJ
I_{AS}	Avalanche Current	34	33.1	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ⁴	46	41.3	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62		$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	5		$^\circ C/W$

Electrical Characteristics (T_C=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	32.5	---	V
ΔBVDSS/ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.0193	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =15A	---	9	12	mΩ
		V _{GS} =4.5V, I _D =10A	---	13	16	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	V
ΔVGS(th)	VGS(th) Temperature Coefficient		---	-3.97	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =24V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =5V, I _D =30A	---	34	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.8	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =15V, V _{GS} =4.5V, I _D =15A	---	9.8	---	nC
Q _{gs}	Gate-Source Charge		---	4.2	---	
Q _{gd}	Gate-Drain Charge		---	3.6	---	
Td(on)	Turn-On Delay Time	V _{DD} =15V, V _{GS} =10V, R _G =3.3Ω I _D =15A	---	4	---	ns
T _r	Rise Time		---	8	---	
Td(off)	Turn-Off Delay Time		---	31	---	
T _f	Fall Time		---	4	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	940	---	pF
C _{oss}	Output Capacitance		---	131	---	
Crss	Reverse Transfer Capacitance		---	109	---	
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	43	A
ISM	Pulsed Source Current ^{2,5}		---	---	112	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time	IF=30A, dI/dt=100A/μs, T _J =25°C	---	8.5	---	nS
Q _{rr}	Reverse Recovery Charge		---	2.2	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2、The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3、The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=10A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

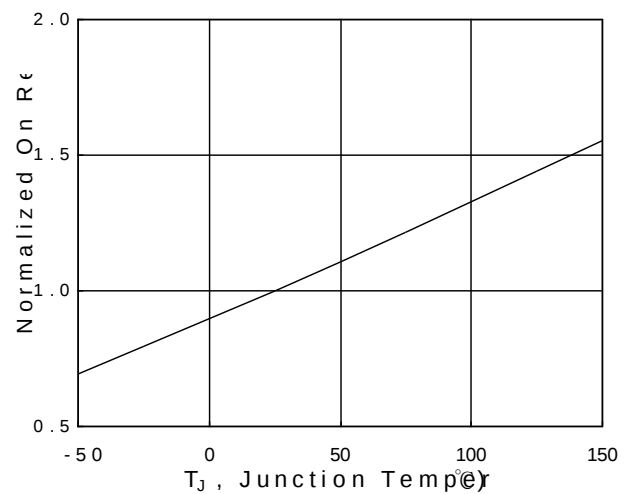
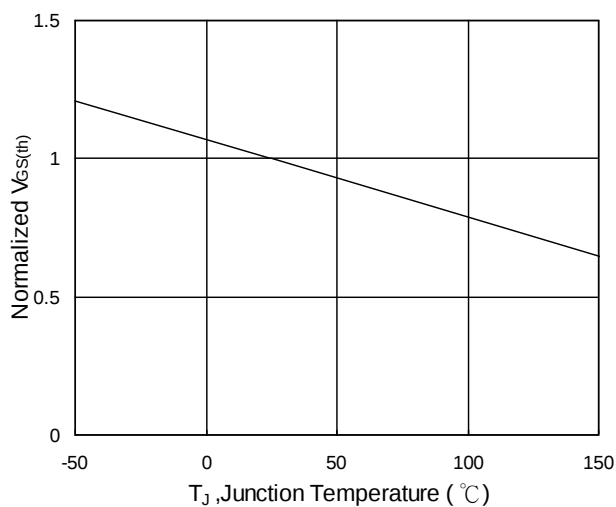
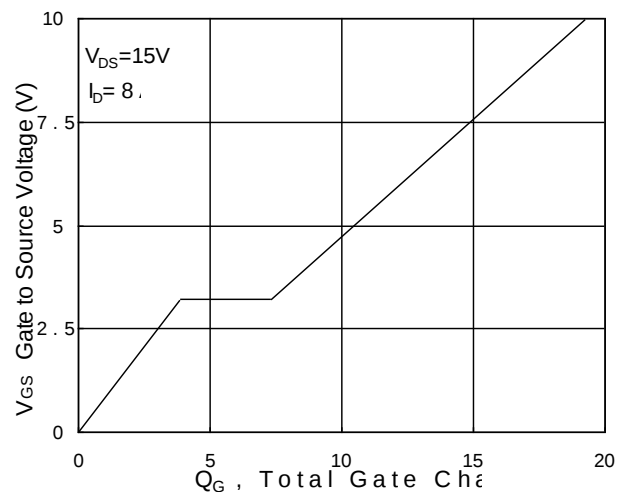
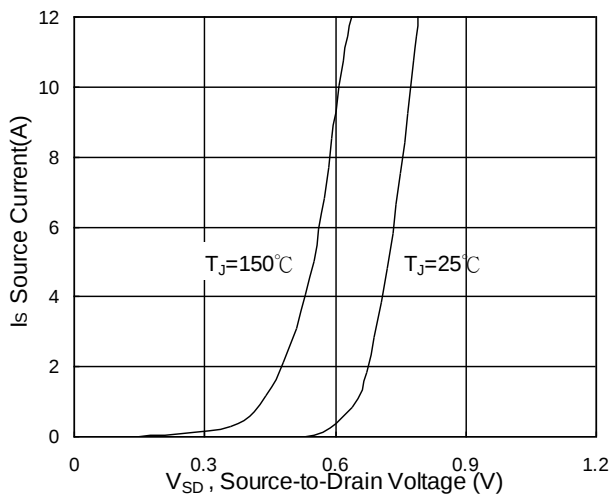
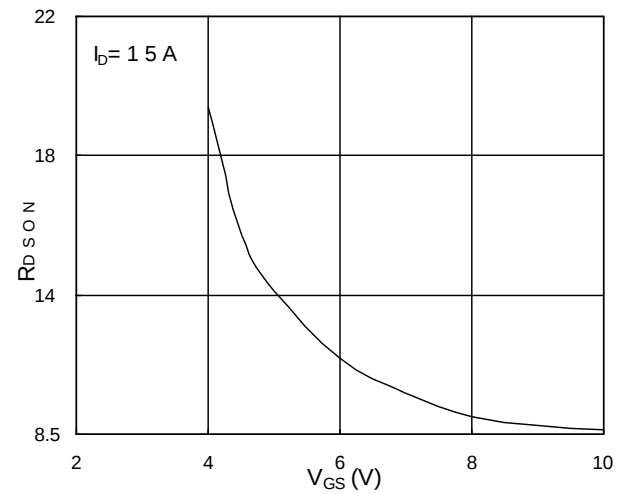
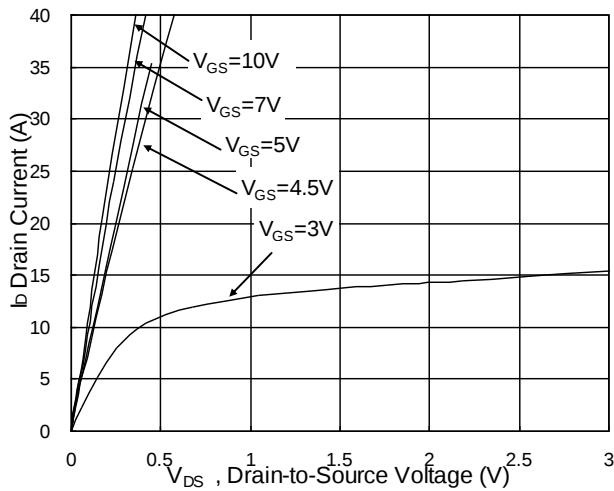
Electrical Characteristics (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	32.5	---	V
ΔBVDSS/ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.022	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-15A	---	21	25	mΩ
		V _{GS} =-4.5V, I _D =-10A	---	33	38	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-2 50uA	-1.0	-1.6	-2.5	V
ΔVGS(th)	VGS(th) Temperature Coefficient		---	4.6	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =-24V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =55°C	---	---	-5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =-5V, I _D =-6A	---	17	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	13	---	Ω
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-6A	---	12.6	---	nC
Q _{gs}	Gate-Source Charge		---	4.8	---	
Q _{gd}	Gate-Drain Charge		---	4.8	---	
Td(on)	Turn-On Delay Time	V _{DD} =-15V, V _{GS} =-10V, R _G =3.3Ω, I _D =-6A	---	4.6	---	ns
T _r	Rise Time		---	14.8	---	
Td(off)	Turn-Off Delay Time		---	41	---	
T _f	Fall Time		---	19.6	---	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	1345	---	pF
C _{oss}	Output Capacitance		---	194	---	
Crss	Reverse Transfer Capacitance		---	158	---	
I _s	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	-6.5	A
ISM	Pulsed Source Current ^{2,5}		---	---	-26	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1.2	V
t _{rr}	Reverse Recovery Time	IF=-6A, dI/dt=100A/μs, T _J =25°C	---	16.3	---	nS
Q _{rr}	Reverse Recovery Charge		---	5.9	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2、The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3、The EAS data shows Max. rating. The test condition is V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-10A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

N-Typical Characteristics



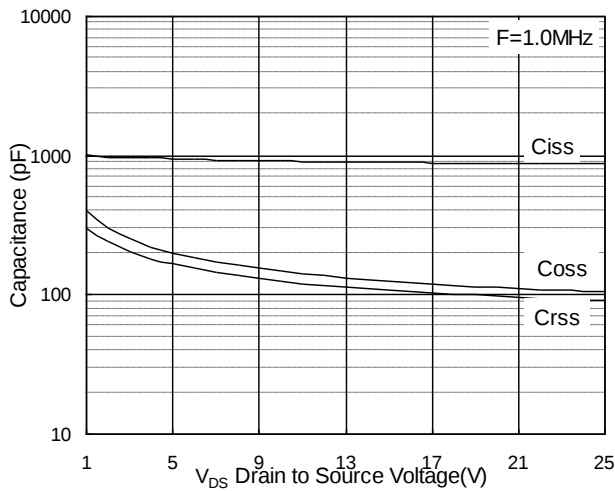


Fig.7 Capacitance

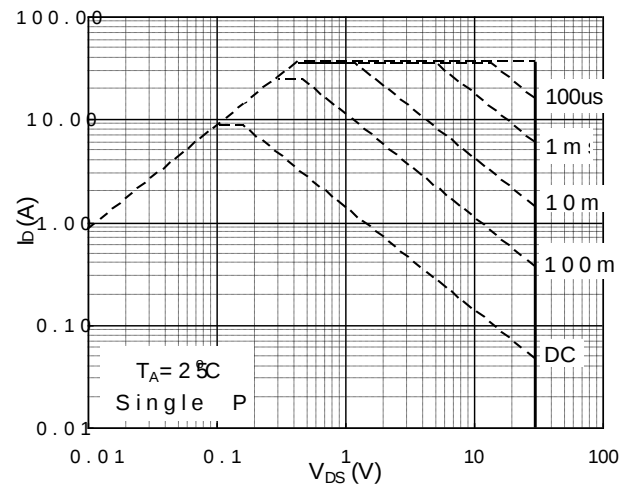


Fig.8 Safe Operating Area

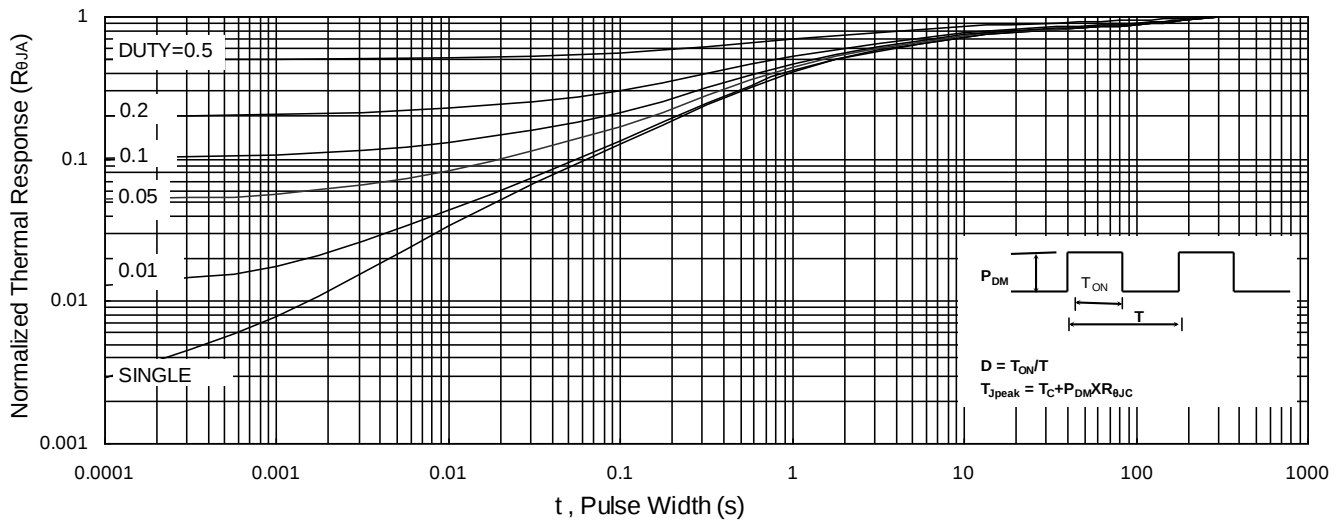


Fig.9 Normalized Maximum Transient Thermal Impedance

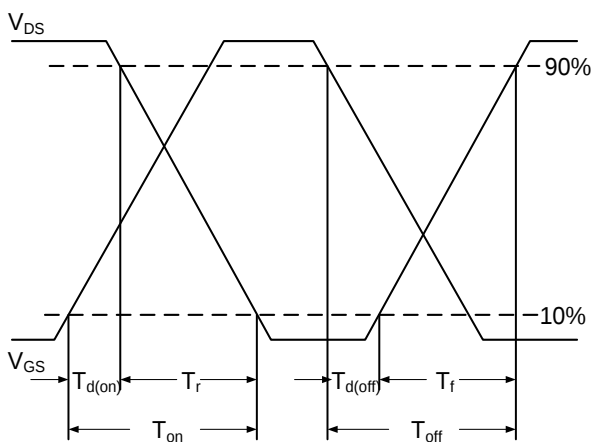


Fig.10 Switching Time Waveform

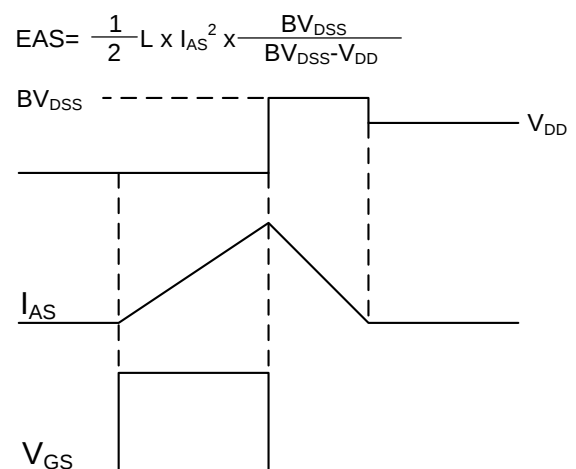
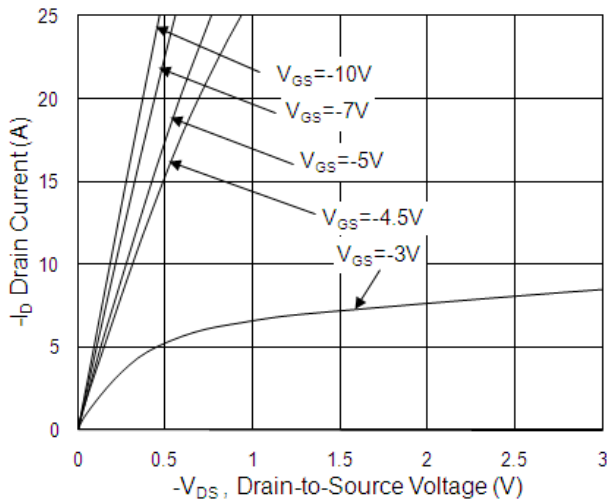
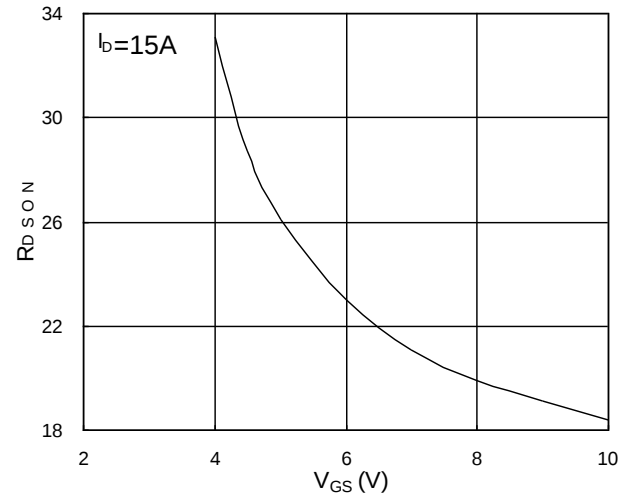
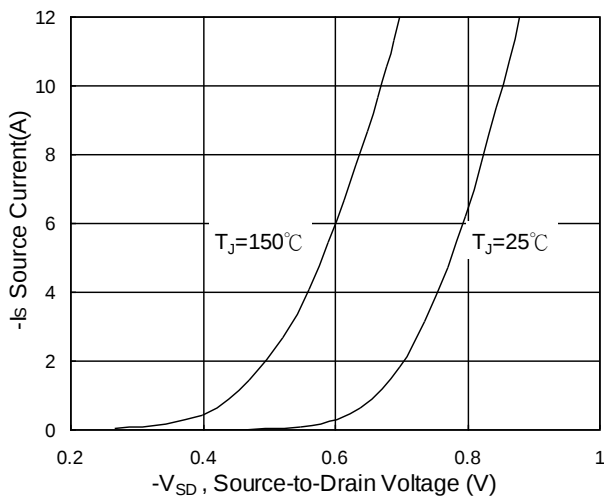
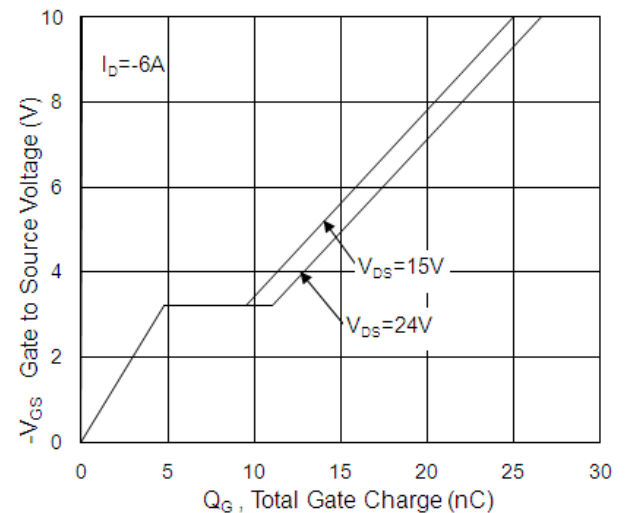
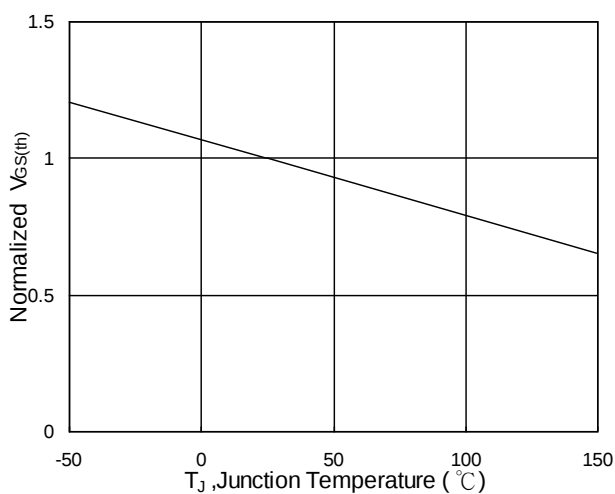
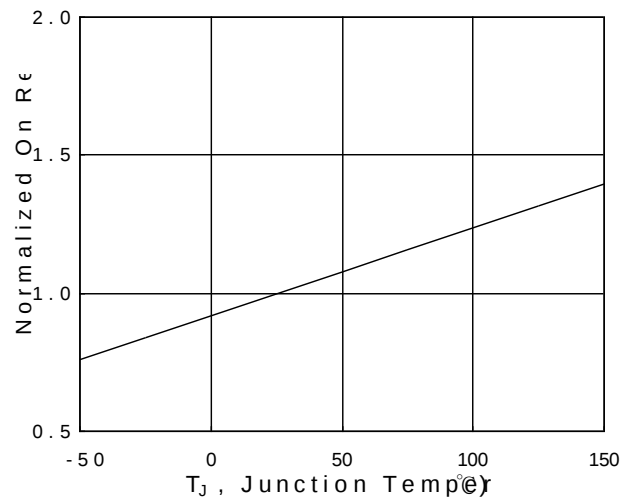


Fig.11 Unclamped Inductive Switching Waveform

P-Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance v.s Gate-Source

Fig.3 Forward Characteristics of Reverse

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ v.s T_J

Fig.6 Normalized $R_{DS(on)}$ v.s T_J

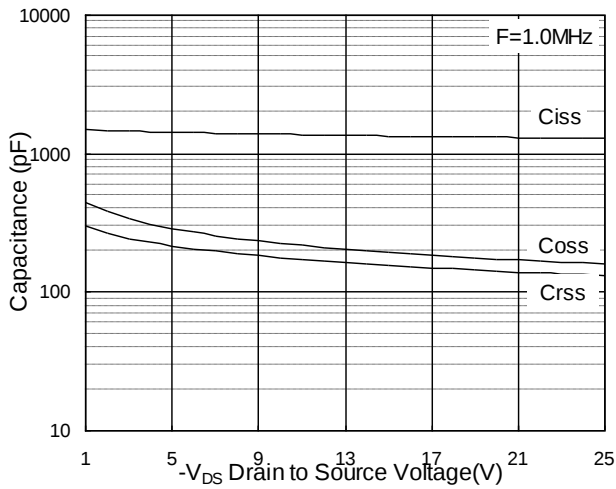


Fig.7 Capacitance

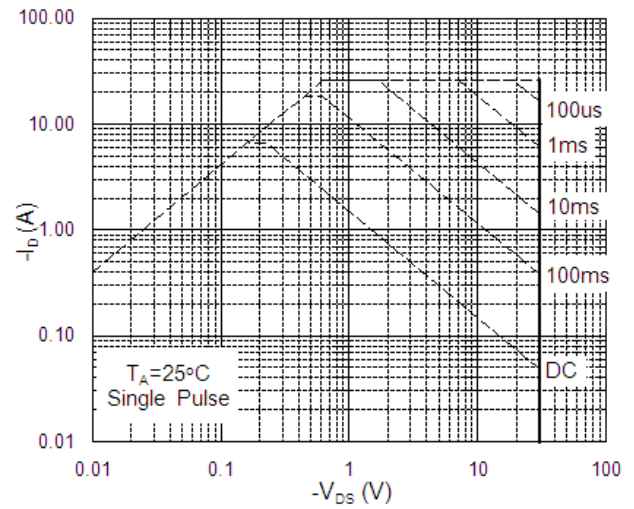


Fig.8 Safe Operating Area

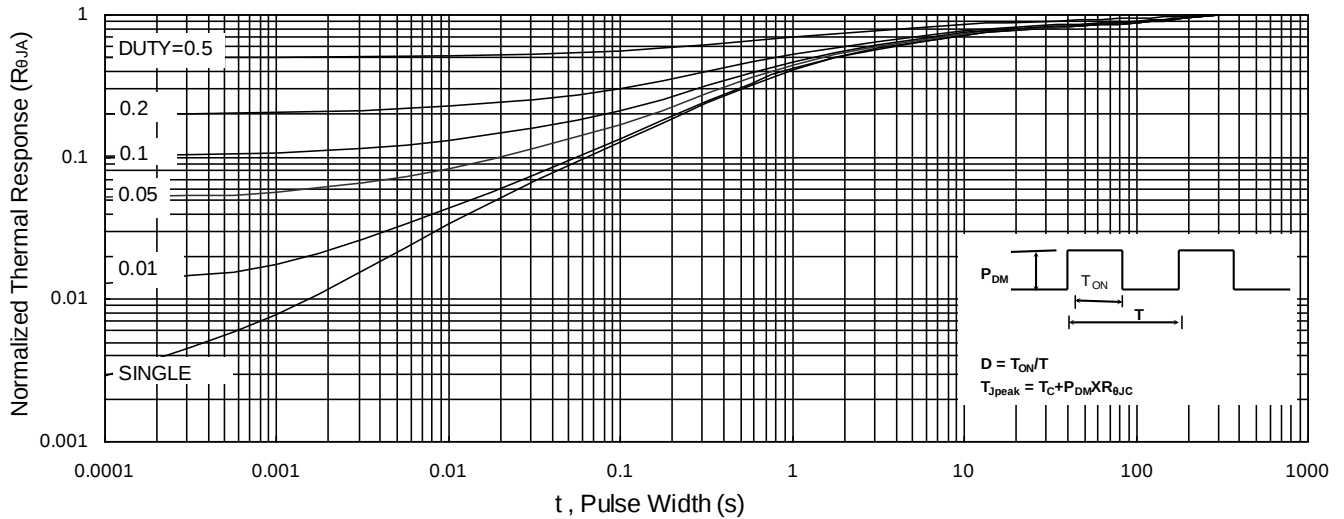


Fig.9 Normalized Maximum Transient Thermal Impedance

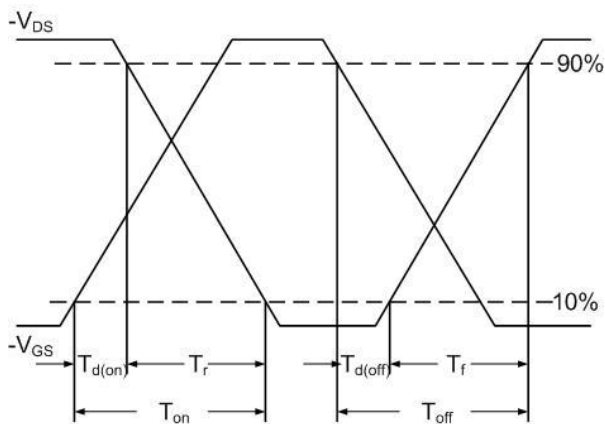


Fig.10 Switching Time Waveform

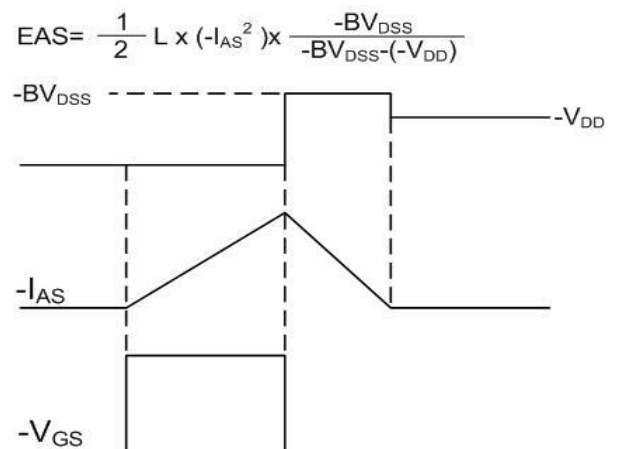
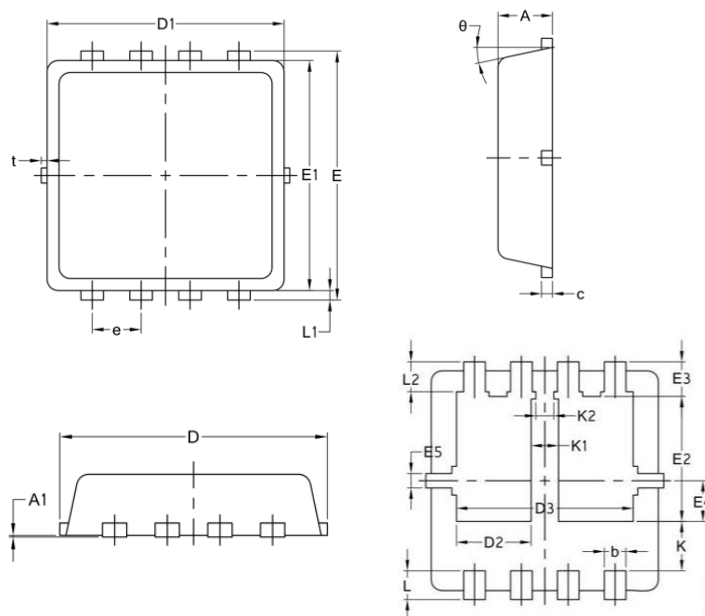


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data-DFN3*3-8L-JQ Double


Symbol	Common		
	Mm		
	Min	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.25	0.30	0.39
c	0.14	0.152	0.20
D	3.20	3.30	3.45
D1	3.05	3.15	3.25
D2	0.84	1.04	1.24
D3	2.30	2.45	2.60
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.60	1.74	1.90
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.50	0.69	0.80
K1	0.30	0.38	0.53
K2	0.15	0.25	0.35
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
L2	0.27	0.42	0.57
t	0	0.075	0.13
Φ	10°	12°	14°